

Datasheet revision 1.2

Solder Wire Sn60/Pb40 No-Clean with 2.0% Flux Core 1oz Spool

Product Highlights No-Clean Synthetic Flux Core The clear, non-corrosive, non-conductive residue is meant to be left on the board. 2.0% flux core Halogen content: None

>60 months

Sn60/Pb40 0.015" (0.38mm) No-Clean Synthetic ROL0 183-188°C (361-370°F) 1 oz spool

Test Results

Specifications

Flux Classification:

Wire Diameter:

Melting Point:

Flux Type:

Packaging:

Shelf Life:

Alloy:

Test J-STD-004 or other requirements as stated	Test Requirement	Result
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.05%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (No-clean)
Surface Insulation Resistance 85°C, 85% RH @ 168 Hours	IPC-TM-650: 2.6.3.7	L: ≥100MΩ (No-clean)
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains Lead (Pb) CAS# 7439-92-1 No other SVHC present

Conforms to the following Industry Standards:J-STD-004B, Amendment 1 (Solder Fluxes):YesJ-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):YesRoHS 3 Directive (EU) 2015/863:No

